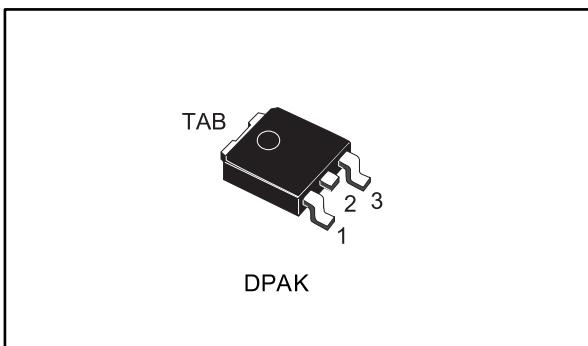
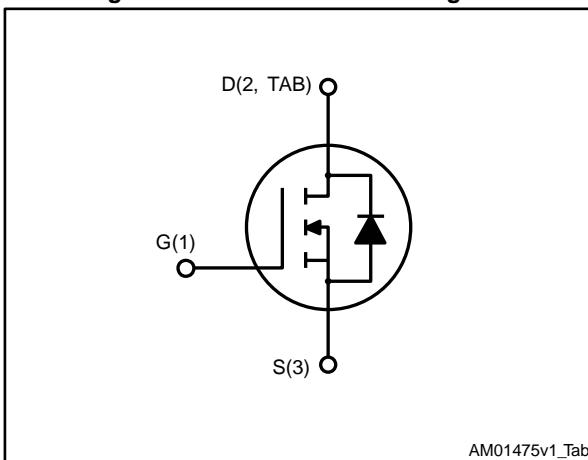


## N-channel 60 V, 4.2 mΩ typ., 80 A STripFET™ F7 Power MOSFET in a DPAK package

Datasheet - production data



**Figure 1: Internal schematic diagram**



### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	I <sub>d</sub>	P <sub>TOT</sub>
STD130N6F7	60 V	5.0 mΩ	80 A	134 W

- Among the lowest R<sub>DS(on)</sub> on the market
- Excellent FoM (figure of merit)
- Low C<sub>rss</sub>/C<sub>iss</sub> ratio for EMI immunity
- High avalanche ruggedness

### Applications

- Switching applications

### Description

This N-channel Power MOSFET utilizes STripFET™ F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

**Table 1: Device summary**

Order code	Marking	Package	Packing
STD130N6F7	130N6F7	DPAK	Tape and reel

## Contents

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# 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	60	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D^{(1)}$	Drain current (continuous) at $T_{case} = 25^\circ C$	80	A
	Drain current (continuous) at $T_{case} = 100^\circ C$	80	
$I_{DM}^{(2)}$	Drain current (pulsed)	320	A
$P_{TOT}$	Total dissipation at $T_{case} = 25^\circ C$	134	W
$E_{AS}^{(3)}$	Single pulse avalanche energy	200	mJ
$dV/dt^{(4)}$	Drain-body diode dynamic $dV/dt$ ruggedness	5.0	V/ns
$T_{stg}$	Storage temperature range	-55 to 175	$^\circ C$
$T_j$	Operating junction temperature range		

**Notes:**

(1) Current is limited by package.

(2) Pulse width is limited by safe operating area.

(3) starting  $T_j = 25^\circ C$ ,  $I_D = 20 A$ ,  $V_{DD} = 30 V$ .(4)  $I_{SD} = 80 A$ ;  $di/dt = 600 A/\mu s$ ;  $V_{DD} = 48 V$ ;  $T_j < T_{jmax}$ 

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	50	$^\circ C/W$
$R_{thj-amb}$	Thermal resistance junction-ambient	1.12	

**Notes:**(1) When mounted on FR-4 board of 1 inch<sup>2</sup>, 2oz Cu,  $t < 10$  sec

## 2 Electrical characteristics

( $T_{case} = 25^\circ C$  unless otherwise specified)

**Table 4: Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 V$ , $I_D = 1 mA$	60			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0 V$ , $V_{DS} = 60 V$			1	$\mu A$
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0 V$ , $V_{GS} = 20 V$			100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	2		4	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10 V$ , $I_D = 40 A$		4.2	5.0	$m\Omega$

**Table 5: Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 30 V$ , $f = 1 MHz$ , $V_{GS} = 0 V$	-	2600	-	pF
$C_{oss}$	Output capacitance		-	1200	-	
$C_{rss}$	Reverse transfer capacitance		-	115	-	
$Q_g$	Total gate charge	$V_{DD} = 30 V$ , $I_D = 80 A$ , $V_{GS} = 10 V$ (see <a href="#">Figure 14: "Test circuit for gate charge behavior"</a> )	-	42	-	nC
$Q_{gs}$	Gate-source charge		-	13.6	-	
$Q_{gd}$	Gate-drain charge		-	13	-	

**Table 6: Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 30 V$ , $I_D = 40 A$ , $R_G = 4.7 \Omega$ , $V_{GS} = 10 V$ (see <a href="#">Figure 13: "Test circuit for resistive load switching times"</a> and <a href="#">Figure 18: "Switching time waveform"</a> )	-	24	-	ns
$t_r$	Rise time		-	44	-	
$t_{d(off)}$	Turn-off delay time		-	62	-	
$t_f$	Fall time		-	24	-	

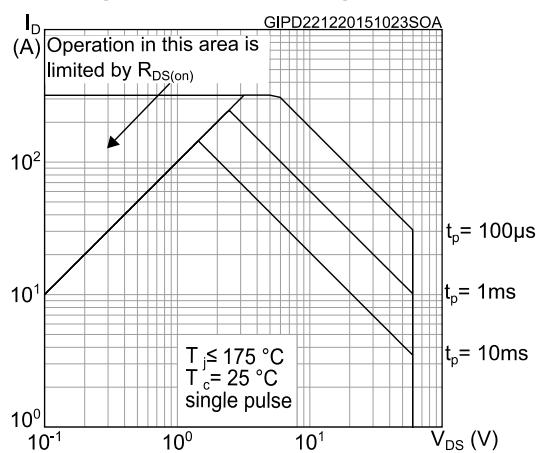
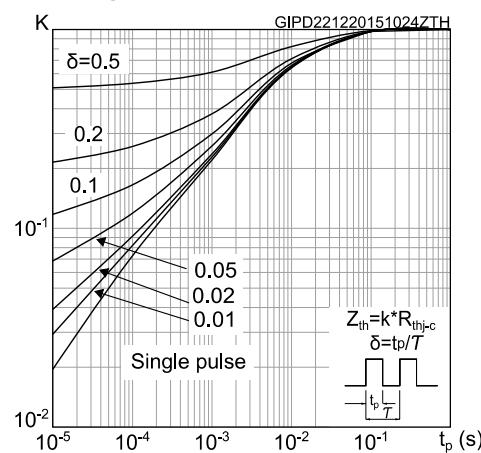
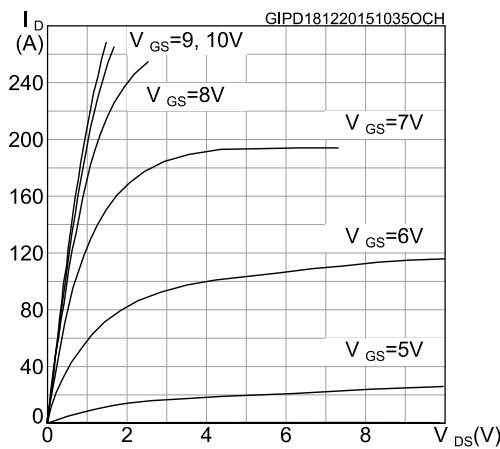
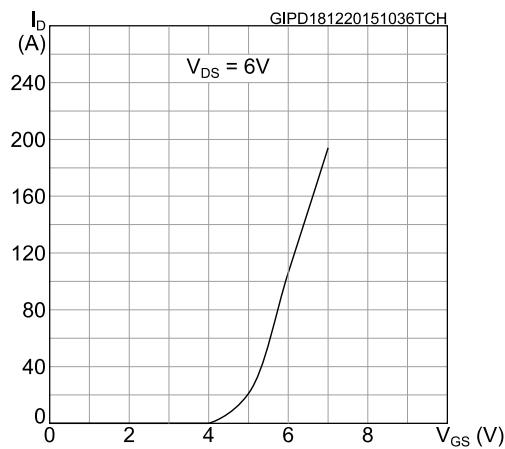
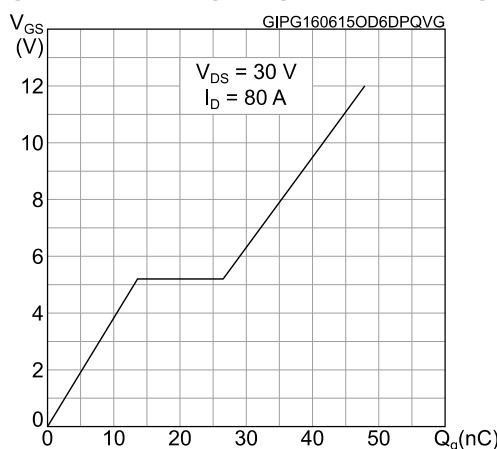
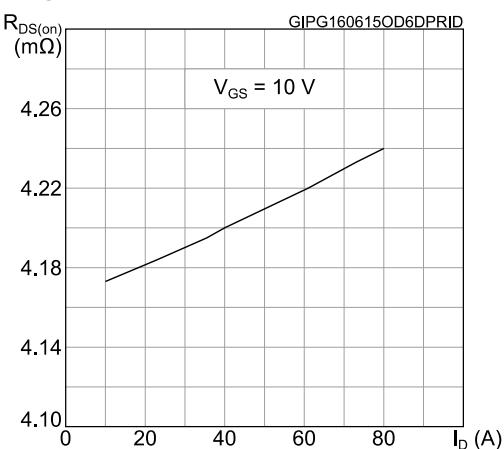
**Table 7: Source-drain diode**

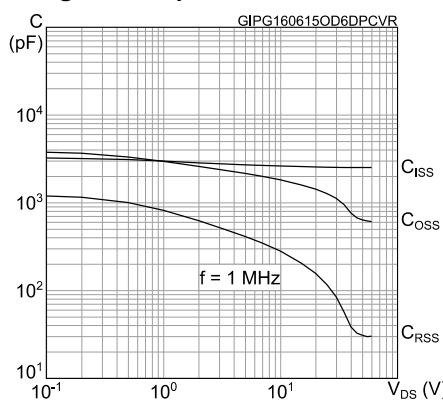
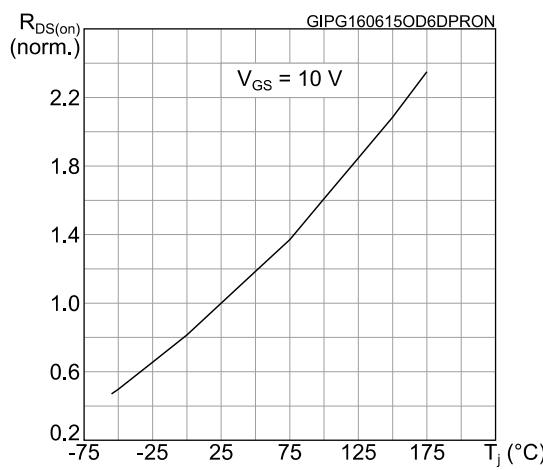
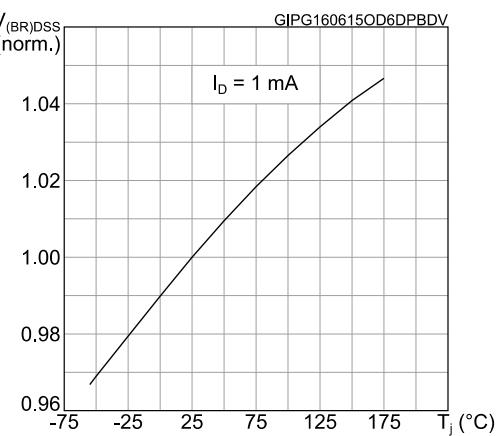
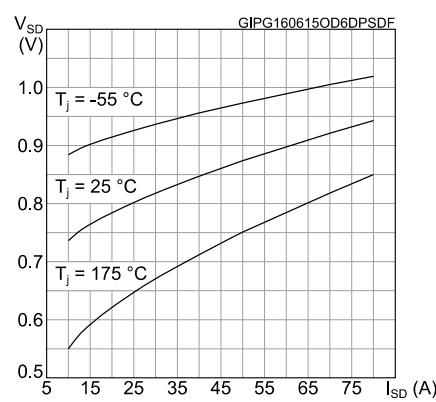
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{SD}^{(1)}$	Forward on voltage	$V_{GS} = 0 V$ , $I_{SD} = 80 A$	-		1.2	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 80 A$ , $di/dt = 100 A/\mu s$ , $V_{DD} = 48 V$ (see <a href="#">Figure 15: "Test circuit for inductive load switching and diode recovery times"</a> )	-	50		ns
$Q_{rr}$	Reverse recovery charge		-	56		nC
$I_{RRM}$	Reverse recovery current		-	2.2		A

**Notes:**

<sup>(1)</sup> Pulse test: pulse duration = 300  $\mu s$ , duty cycle 1.5%.

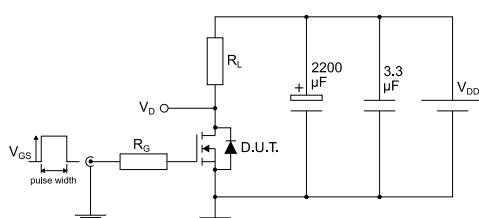
## 2.1 Electrical characteristics (curves)

**Figure 2: Safe operating area****Figure 3: Thermal impedance****Figure 4: Output characteristics****Figure 5: Transfer characteristics****Figure 6: Gate charge vs gate-source voltage****Figure 7: Static drain-source on-resistance**

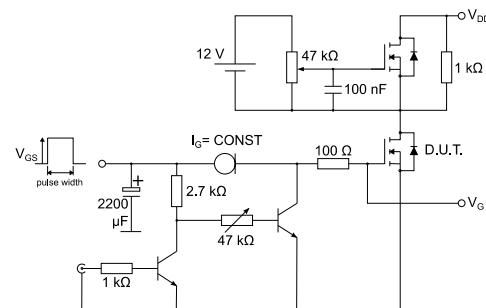
**Figure 8: Capacitance variations****Figure 9: Normalized gate threshold voltage vs temperature****Figure 10: Normalized on-resistance vs temperature****Figure 11: Normalized V(BR)DSS vs temperature****Figure 12: Source-drain diode forward characteristics**

### 3 Test circuits

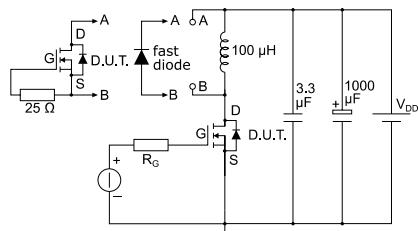
**Figure 13: Test circuit for resistive load switching times**



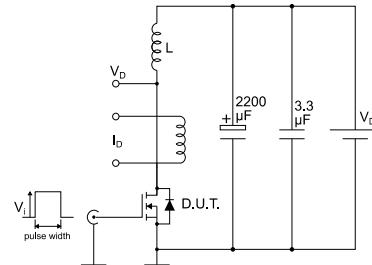
**Figure 14: Test circuit for gate charge behavior**



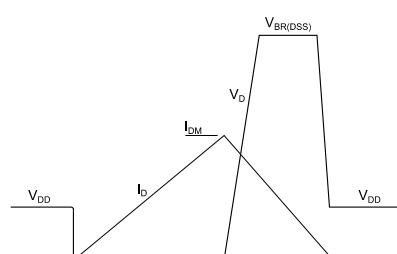
**Figure 15: Test circuit for inductive load switching and diode recovery times**



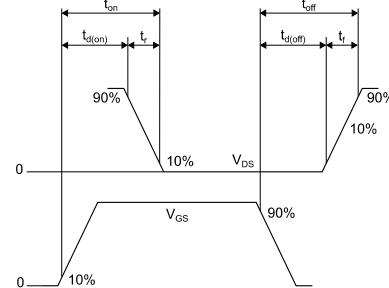
**Figure 16: Unclamped inductive load test circuit**



**Figure 17: Unclamped inductive waveform**



**Figure 18: Switching time waveform**

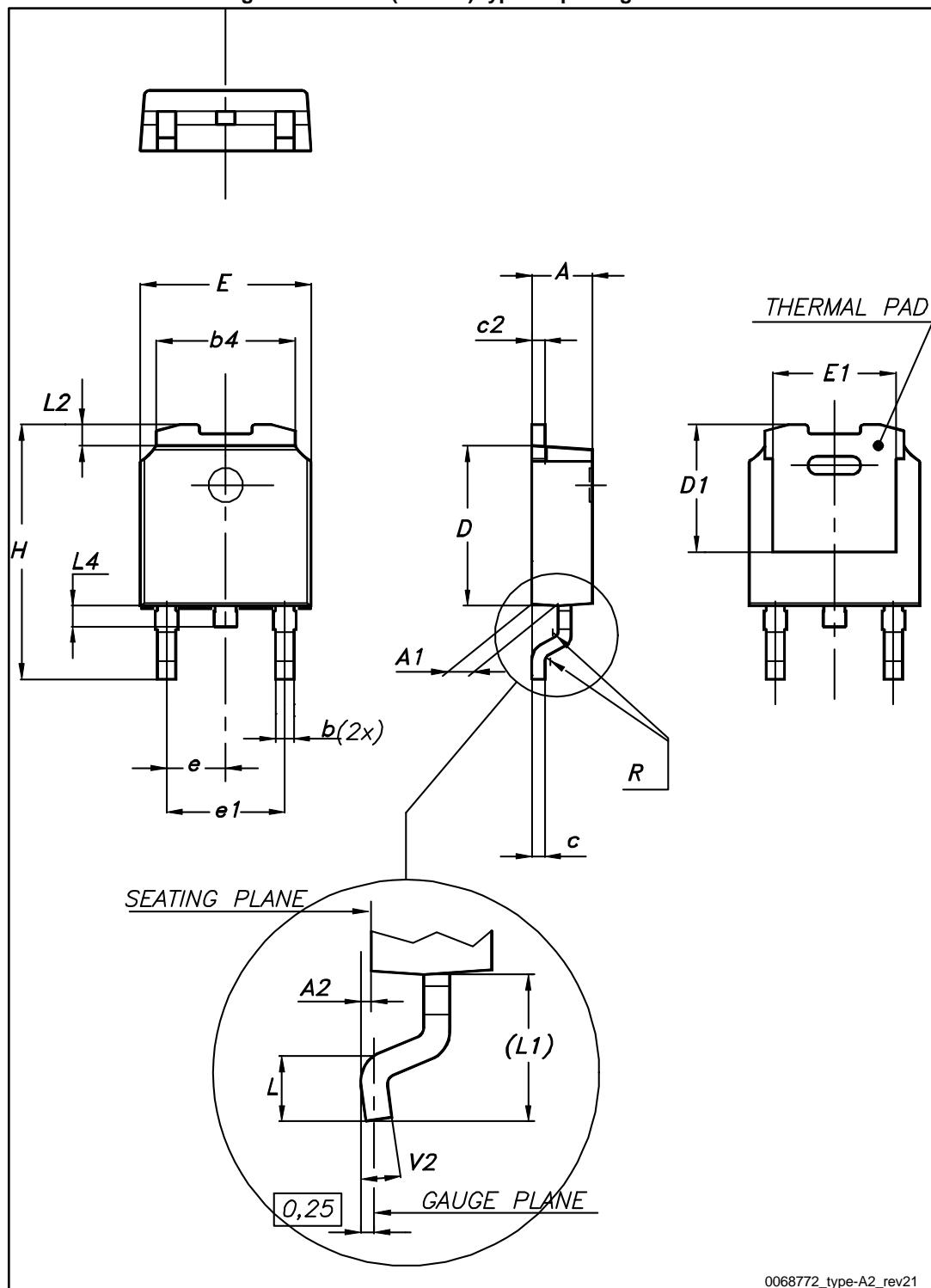


## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
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## 4.1 DPAK package information

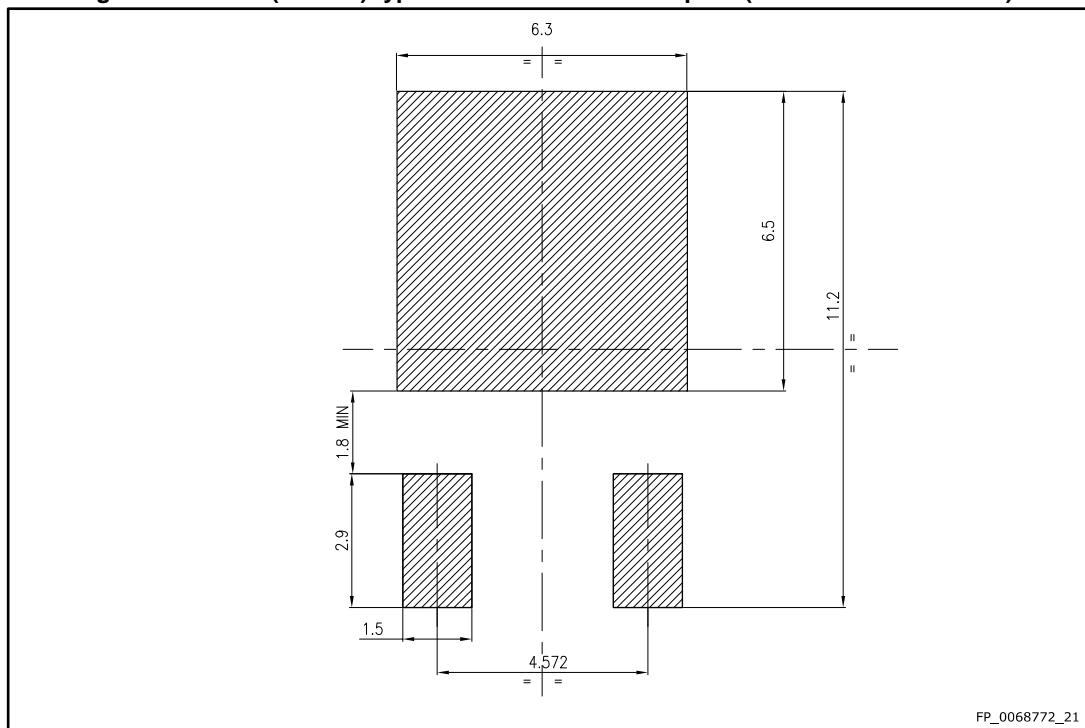
Figure 19: DPAK (TO-252) type A2 package outline



**Table 8: DPAK (TO-252) type A2 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	5.10	5.20	5.30
e	2.16	2.28	2.40
e1	4.40		4.60
H	9.35		10.10
L	1.00		1.50
L1	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

Figure 20: DPAK (TO-252) type A2 recommended footprint (dimensions are in mm)



FP\_0068772\_21

## 5 Revision history

Table 9: Document revision history

Date	Revision	Changes
17-Dec-2015	1	First release.
10-Oct-2016	2	Document status changed from preliminary to production data. Minor text changes.

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